

## SCM1100M Series

 Support for 3-shunt, Output Element : IGBT

### ■Features

- Each half-bridge circuit consists of a pre-driver circuit that is completely independent from the others
- Protection against simultaneous high- and low-side turning on
- Bootstrap diodes with series resistors for suppressing inrush current are incorporated
- CMOS compatible input (3.3 to 5 V)
- Designed to minimize simultaneous current through both high- and low-side IGBTs by optimizing gate drive resistors
- UVLO protection with auto restart
- Overcurrent protection with off-time period adjustable by an external capacitor
- Fault (FO indicator) signal output at protection activation: UVLO (low side only), OCP, and STP
- Proprietary power DIP package
- UL Recognized Component (File No.: E118037)

### ■Absolute Maximum Ratings

Parameter	Symbol	Ratings						Unit	Conditions
		SCM1101M (SCM1101MF)	SCM1103M	SCM1104M (SCM1104MF)	SCM1105MF	SCM1106M (SCM1106MF)	SCM1110MF		
Supply Voltage	V <sub>BB</sub>	450	450	450	450	450	450	V	Between V <sub>BB</sub> and LS1 to LS3
Supply Voltage (Surge)	V <sub>DC(Surge)</sub>	500	500	500	500	500	500	V	Between V <sub>BB</sub> and LS1 to LS3
IGBT Output Withstand Voltage	V <sub>CES</sub>	600	600	600	600	600	600	V	V <sub>CC</sub> =15V, I <sub>C</sub> =1mA, V <sub>IN</sub> =0V
Control Supply Voltage	V <sub>CC</sub>	20	20	20	20	20	20	V	V <sub>CC1</sub> to 3 and COM1 to COM3
Control Supply Voltage (Bootstrap)	V <sub>SS</sub>	20	20	20	20	20	20	V	V <sub>B1</sub> to V <sub>B3</sub> and HS (U,V,W)
Output Current (continuous)	I <sub>O</sub>	10	5	8	15	10	15	Adc	
Output Current (pulse)	I <sub>OP</sub>	20	10	16	30	20	30	Adc	T <sub>S</sub> ≤1ms
Input Voltage	V <sub>IN</sub>	-0.5 to +7	-0.5 to +7	-0.5 to +7	-0.5 to +7	-0.5 to +7	-0.5 to +7	V	H <sub>IN1</sub> to H <sub>IN3</sub> or L <sub>IN1</sub> to L <sub>IN3</sub> and COM1 to COM3
FO Pin Voltage	V <sub>FO</sub>	7	7	7	7	7	7	V	F <sub>O1</sub> to F <sub>O3</sub> and COM1 to COM3
Power Dissipation	P <sub>D</sub>	20.8(33.8)	19	20.2(32.9)	41.7	20.8(33.8)	41.7	W	T <sub>C</sub> =25°C while one IGBT element operates
Thermal Resistance (IGBT)	R <sub>(j-c)Q</sub>	6(3.7)	6.3	6.2(3.8)	3	6(3.7)	3	°C/W	Per IGBT element
Thermal Resistance (FRD)	R <sub>(j-c)F</sub>	6.5(4.2)	6.5	6.5(4.2)	4	6.5(4.2)	4	°C/W	Per FRD element
Operating Case Temperature	T <sub>OP</sub>	-20 to +100	-20 to +100	-20 to +100	-20 to +100	-20 to +100	-20 to +100	°C	
Junction Temperature	T <sub>j</sub>	150	150	150	150	150	150	°C	
Storage Temperature	T <sub>STG</sub>	-40 to +150	-40 to +150	-40 to +150	-40 to +150	-40 to +150	-40 to +150	°C	
Insulation Withstand Voltage	V <sub>ISO</sub>	2000	2000	2000	2000	2000	2000	V	Between rear and lead pins, AC one minute

### ■Recommended Operating Conditions

Parameter	Symbol	Ratings			Unit	Conditions
		SCM1100M Series				
Main Supply Voltage	V <sub>DC</sub>	—	300	400	V	Between V <sub>BB</sub> and LS
Control Supply Voltage	V <sub>CC, V<sub>BS</sub></sub>	13.5	—	16.5	V	
Minimum Input Pulse Width	t <sub>INmin(on)</sub>	0.5	—	—	μs	ON pulse
	t <sub>INmin(off)</sub>	0.5	—	—	μs	OFF pulse
Input Signal Dead Time	t <sub>dead</sub>	1.5	—	—	μs	
FO Pull-up Resistor	R <sub>FO</sub>	1	—	22	kΩ	
CFO Capacitor Capacity	C <sub>FO</sub>	1	—	10	nF	
FO Pull-up Voltage	V <sub>FO</sub>	4.5	—	5.5	V	
Boot Capacitor	C <sub>BOOT</sub>	10	—	220	uF	
Shunt Resistor <sup>1</sup>	R <sub>S</sub>	25.5	—	—	mΩ	For I <sub>OP</sub> ≤rated output current (pulse)
PWM Carrier Frequency	f <sub>C</sub>	—	—	20 <sup>2</sup>	kHz	
Junction Temperature	T <sub>j</sub>	—	—	125	°C	

\*1: The shunt resistance varies depending on the rated current.

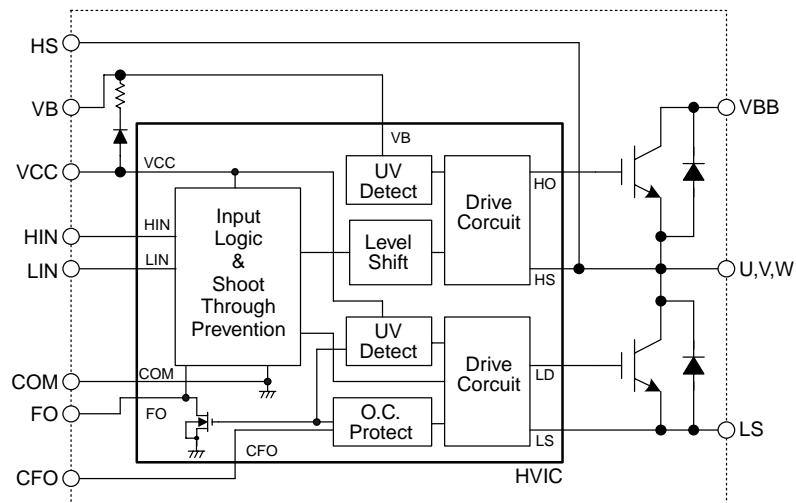
\*2: 10 for SCM1101M(F)/SCM1105MF

## ■ Electrical Characteristics

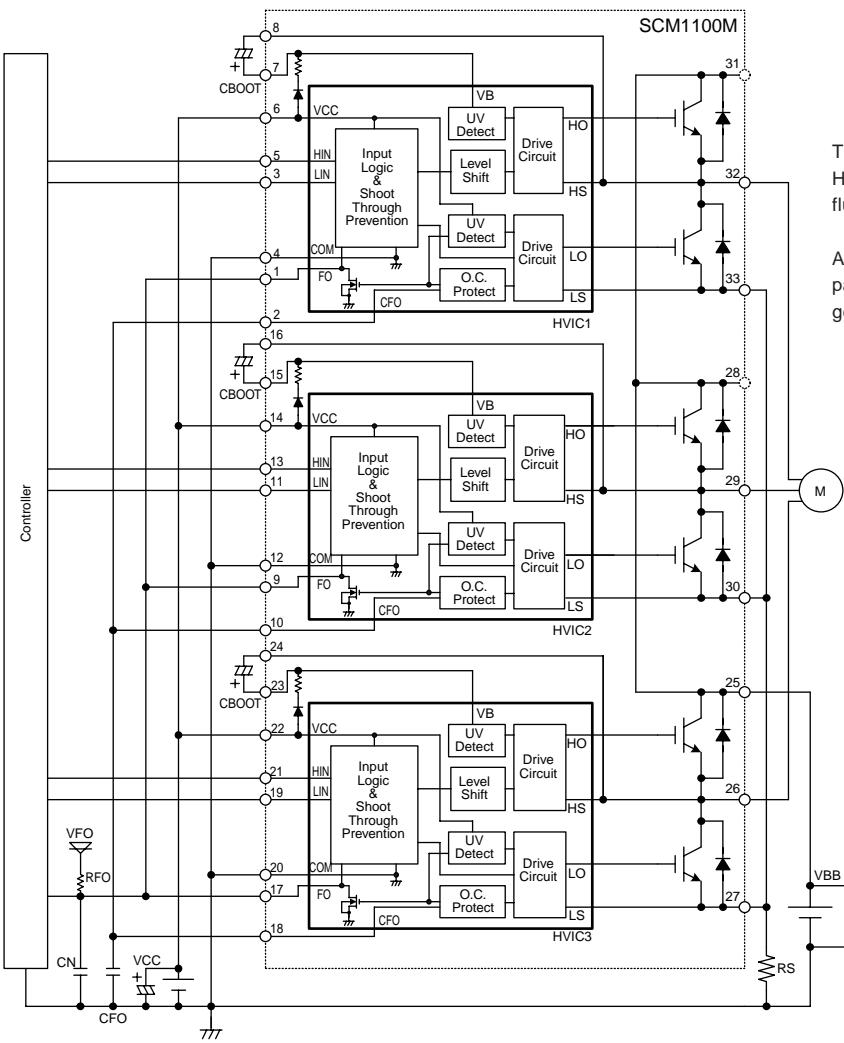
Parameter	Symbol	Ratings								Unit	Conditions	
		SCM1101M/SCM1101MF			SCM1103M			SCM1104M/SCM1104MF				
		min.	typ.	max.	min.	typ.	max.	min.	typ.	max.		
Control Supply Voltage	V <sub>CC</sub>	13.5	—	16.5	13.5	—	16.5	13.5	—	16.5	V	Between V <sub>CC</sub> and COM
Control Supply Current	I <sub>CC</sub>	—	5	8	—	5	8	—	5	8	mA	V <sub>CC</sub> =15V, 3 circuits total
Bootstrap Supply Current	I <sub>BS</sub>	—	400	800	—	400	800	—	400	800	uA	V <sub>S-HS</sub> =15V, 1 circuit
Input Voltage	V <sub>IH</sub>	—	2	2.5	—	2	2.5	—	2	2.5	V	V <sub>CC</sub> =15V, Output:ON
	V <sub>IL</sub>	1	1.5	—	1	1.5	—	1	1.5	—	V	V <sub>CC</sub> =15V, Output:OFF
Input Voltage Hysteresis Width	V <sub>H</sub>	—	0.5	—	—	0.5	—	—	0.5	—	V	V <sub>CC</sub> =15V
	I <sub>IH</sub>	—	50	100	—	50	100	—	50	100	μA	V <sub>CC</sub> =15V, V <sub>IN</sub> =5V
Input Current	I <sub>IL</sub>	—	—	2	—	—	2	—	—	2	μA	V <sub>CC</sub> =15V, V <sub>IN</sub> =0V
	V <sub>UVHL</sub>	10	—	12	10	—	12	10	—	12	V	V <sub>CC</sub> =15V
Undervoltage Lock Out (high side)	V <sub>UVHH</sub>	10.5	—	12.5	10.5	—	12.5	10.5	—	12.5	V	
	V <sub>UVLL</sub>	10.5	—	12.5	10.5	—	12.5	10.5	—	12.5	V	
Undervoltage Lock Out (low side)	V <sub>UVLH</sub>	11	—	13	11	—	13	11	—	13	V	
	V <sub>FOL</sub>	—	—	0.5	—	—	0.5	—	—	0.5	V	V <sub>CC</sub> =15V, V <sub>FO</sub> =5V
FO Pin Output Voltage	V <sub>F0H</sub>	4.8	—	—	4.8	—	—	4.8	—	—	V	R <sub>FO</sub> =10kΩ
	V <sub>TRIP</sub>	0.46	0.5	0.54	0.46	0.5	0.54	0.46	0.5	0.54	V	V <sub>CC</sub> =15V
Overcurrent Protection Trip Voltage	t <sub>P</sub>	2	—	—	2	—	—	2	—	—	ms	V <sub>CC</sub> =15V, C <sub>FO</sub> =2.2nF
	t <sub>bk</sub>	—	2	—	—	2	—	—	2	—	μs	V <sub>CC</sub> =15V
IGBT Output Withstand Voltage	V <sub>CES</sub>	600	—	—	600	—	—	600	—	—	V	V <sub>CC</sub> =15V, I <sub>C</sub> =1mA, V <sub>IN</sub> =0V
IGBT Output Leakage Current	I <sub>CES</sub>	—	—	1	—	—	1	—	—	1	mA	V <sub>CC</sub> =15V, V <sub>CE</sub> =600V, V <sub>IN</sub> =0V
IGBT Output Saturation Voltage	V <sub>CE(sat)</sub>	—	1.75	2.2	—	1.7	2.1	—	1.75	2.2	V	V <sub>CC</sub> =15V, I <sub>C</sub> =rated output current (continuous) V <sub>IN</sub> =5V
Boot Diode Forward Voltage	V <sub>F</sub>	—	1.7	2.2	—	1.4	2	—	1.6	2.2	V	V <sub>CC</sub> =15V, I <sub>F</sub> =rated output current (continuous), V <sub>IN</sub> =0V
Boot Diode Leakage Current	I <sub>IB</sub>	—	5	10	—	5	10	—	5	10	μA	V <sub>R</sub> =600V
Boot Diode Forward Voltage	V <sub>FB</sub>	—	1.1	1.3	—	1.1	1.3	—	1.1	1.3	V	I <sub>F</sub> =0.15A
Boot Diode Recovery Time	t <sub>rr</sub>	—	70	—	—	70	—	—	70	—	ns	I <sub>F</sub> /I <sub>RP</sub> =100mA/100mA
Boot Diode Series Resistance	R <sub>B</sub>	17.6	22	26.4	17.6	22	26.4	17.6	22	26.4	Ω	
High Side Switching Time	td(on)	—	320	—	—	340	—	—	360	—	ns	V <sub>D</sub> =300V, V <sub>CC</sub> =15V I <sub>C</sub> =10A(SCM1101M), I <sub>C</sub> =5A(SCM1103M), I <sub>C</sub> =8A(SCM1104M) HIN=0 to 5V Inductive load
	tr	—	50	—	—	60	—	—	70	—		
	t <sub>rr</sub>	—	80	—	—	80	—	—	80	—		
	td(off)	—	560	—	—	430	—	—	560	—		
	tf	—	210	—	—	240	—	—	210	—		
Low Side Switching Time	td(on)	—	350	—	—	380	—	—	420	—	ns	V <sub>D</sub> =300V, V <sub>CC</sub> =15V I <sub>C</sub> =10A(SCM1101M), I <sub>C</sub> =5A(SCM1103M), I <sub>C</sub> =8A(SCM1104M) HIN=0 to 5V Inductive load
	tr	—	80	—	—	90	—	—	110	—		
	t <sub>rr</sub>	—	140	—	—	100	—	—	140	—		
	td(off)	—	610	—	—	500	—	—	630	—		
	tf	—	200	—	—	220	—	—	210	—		

Parameter	Symbol	Ratings								Unit	Conditions	
		SCM1105MF			SCM1106M/SCM1106MF			SCM110MF				
		min.	typ.	max.	min.	typ.	max.	min.	typ.	max.		
Control Supply Voltage	V <sub>CC</sub>	13.5	—	16.5	13.5	—	16.5	13.5	—	16.5	V	Between V <sub>CC</sub> and COM
Control Supply Current	I <sub>CC</sub>	—	5	8	—	5	8	—	5	8	mA	V <sub>CC</sub> =15V, 3 circuits total
Bootstrap Supply Current	I <sub>BS</sub>	—	400	800	—	400	800	—	400	800	uA	V <sub>S-HS</sub> =15V, 1 circuit
Input Voltage	V <sub>IH</sub>	—	2	2.5	—	2	2.5	—	2	2.5	V	V <sub>CC</sub> =15V, Output:ON
	V <sub>IL</sub>	1	1.5	—	1	1.5	—	1	1.5	—	V	V <sub>CC</sub> =15V, Output:OFF
Input Voltage Hysteresis Width	V <sub>H</sub>	—	0.5	—	—	0.5	—	—	0.5	—	V	V <sub>CC</sub> =15V
	I <sub>IH</sub>	—	50	100	—	50	100	—	50	100	μA	V <sub>CC</sub> =15V, V <sub>IN</sub> =5V
Input Current	I <sub>IL</sub>	—	—	2	—	—	2	—	—	2	μA	V <sub>CC</sub> =15V, V <sub>IN</sub> =0V
	V <sub>UVHL</sub>	10	—	12	10	—	12	10	—	12	V	V <sub>CC</sub> =15V
Undervoltage Lock Out (high side)	V <sub>UVHH</sub>	10.5	—	12.5	10.5	—	12.5	10.5	—	12.5	V	
	V <sub>UVLL</sub>	10.5	—	12.5	10.5	—	12.5	10.5	—	12.5	V	
Undervoltage Lock Out (low side)	V <sub>UVLH</sub>	11	—	13	11	—	13	11	—	13	V	
	V <sub>FOL</sub>	—	—	0.5	—	—	0.5	—	—	0.5	V	V <sub>CC</sub> =15V, V <sub>FO</sub> =5V
FO Pin Output Voltage	V <sub>F0H</sub>	4.8	—	—	4.8	—	—	4.8	—	—	V	R <sub>FO</sub> =10kΩ
	V <sub>TRIP</sub>	0.46	0.5	0.54	0.46	0.5	0.54	0.46	0.5	0.54	V	V <sub>CC</sub> =15V
Overcurrent Protection Trip Voltage	t <sub>P</sub>	2	—	—	2	—	—	2	—	—	ms	V <sub>CC</sub> =15V, C <sub>FO</sub> =2.2nF
	t <sub>bk</sub>	—	2	—	—	2	—	—	2	—	μs	V <sub>CC</sub> =15V
IGBT Output Withstand Voltage	V <sub>CES</sub>	600	—	—	600	—	—	600	—	—	V	V <sub>CC</sub> =15V, I <sub>C</sub> =1mA, V <sub>IN</sub> =0V
IGBT Output Leakage Current	I <sub>CES</sub>	—	—	1	—	—	1	—	—	1	mA	V <sub>CC</sub> =15V, V <sub>CE</sub> =600V, V <sub>IN</sub> =0V
IGBT Output Saturation Voltage	V <sub>CE(sat)</sub>	—	1.75	2.2	—	2.2	2.6	—	2.2	2.6	V	V <sub>CC</sub> =15V, I <sub>C</sub> =rated output current (continuous) V <sub>IN</sub> =5V
Boot Diode Forward Voltage	V <sub>F</sub>	—	1.75	2.2	—	1.7	2.2	—	1.75	2.2	V	V <sub>CC</sub> =15V, I <sub>F</sub> =rated output current (continuous), V <sub>IN</sub> =0V
Boot Diode Leakage Current	I <sub>IB</sub>	—	5	10	—	5	10	—	5	10	μA	V <sub>R</sub> =600V
Boot Diode Forward Voltage	V <sub>FB</sub>	—	1.1	1.3	—	1.1	1.3	—	1.1	1.3	V	I <sub>F</sub> =0.15A
Boot Diode Recovery Time	t <sub>rr</sub>	—	70	—	—	70	—	—	70	—	ns	I <sub>F</sub> /I <sub>RP</sub> =100mA/100mA
Boot Diode Series Resistance	R <sub>B</sub>	17.6	22	26.4	17.6	22	26.4	17.6	22	26.4	Ω	
High Side Switching Time	td(on)	—	365	—	—	320	—	—	365	—	ns	V <sub>D</sub> =300V, V <sub>CC</sub> =15V I <sub>C</sub> =15A(SCM1105M), I <sub>C</sub> =10A(SCM1106M), I <sub>C</sub> =15A(SCM1110MF) HIN=0 to 5V Inductive load
	tr	—	80	—	—	50	—	—	80	—		
	t <sub>rr</sub>	—	90	—	—	80	—	—	90	—		
	td(off)	—	690	—	—	490	—	—	650	—		
	tf	—	200	—	—	80	—	—	85	—		
Low Side Switching Time	td(on)	—	415	—	—	350	—	—	415	—	ns	V <sub>D</sub> =300V, V <sub>CC</sub> =15V I <sub>C</sub> =15A(SCM1105M), I <sub>C</sub> =10A(SCM1106M), I <sub>C</sub> =15A(SCM1110MF) HIN=0 to 5V Inductive load
	tr	—	135	—	—	80	—	—	135	—		
	t <sub>rr</sub>	—	115	—	—	140	—	—	115	—		
	td(off)	—	790	—	—	540	—	—	755	—		
	tf	—	205	—	—	80	—	—	85	—		

## ■ Internal Block Diagram (Single Circuit)



## ■ Typical Connection Diagram

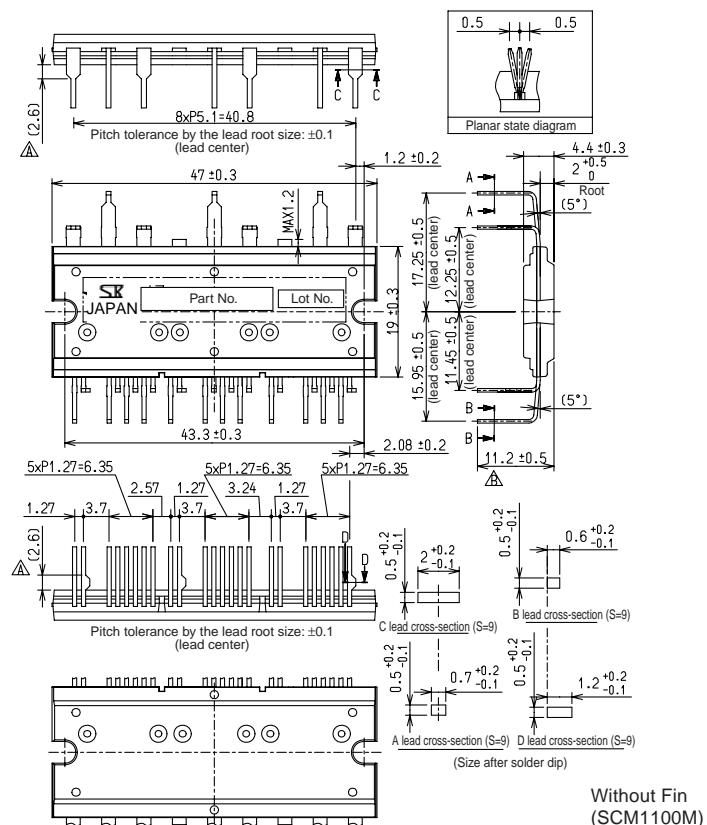


The input pulldown resistor is built in IC (about 100 kΩ). However, if the input is expected to be unstable or very fluctuant, it needs to be reinforced with external resistor.

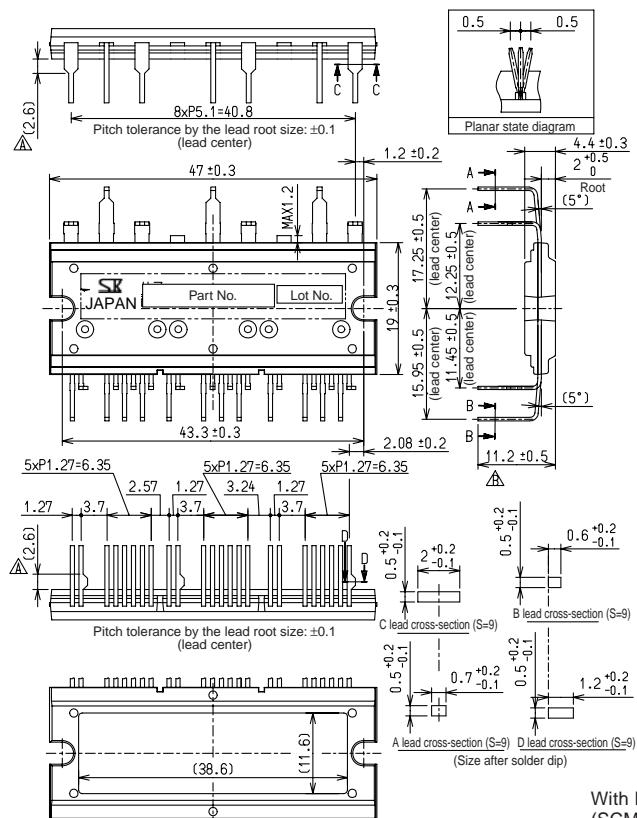
Attach capacitors near IC. Attach a ceramic capacitor in parallel with the electrolytic capacitor if too much noise is generated.

## ■ External Dimensions (SCM)

(Unit : mm)



Forming No. 2551  
Product Mass: Approx. 12.6g



With Fin  
(SCM1100MF) Forming No. 2552  
Product Mass: Approx. 13.5g